



IEC DESIGN AUTOMATIN STANDARDIZATION

presented by

Alex Zamfirescu

TC
93



Structure





TC 93 Membership

AUSTRALIA (AU)	O	ITALY (IT)	O
BELGIUM (BE)	O	<u>JAPAN (JP)</u>	P
<u>CHINA (CN)</u>	P	KOREA (REPUBLIC OF) (KR)	O
<u>CZECH REPUBLIC (CZ)</u>	P	NETHERLANDS (NL)	O
DENMARK (DK)	O	<u>RUSSIAN FEDERATION (RU)</u>	P
EGYPT (EG)	O	SERBIA AND MONTENEGRO (CS)	O
<u>FINLAND (FI)</u>	P	SINGAPORE (SG)	O
FRANCE (FR)	O	<u>SPAIN (ES)</u>	P
GERMANY (DE)	O	SWEDEN (SE)	O
HUNGARY (HU)	O	UKRAINE (UA)	O
INDIA (IN)	O	<u>UNITED KINGDOM (GB)</u>	P
IRELAND (IE)	O	<u>UNITED STATES OF AMERICA (US)</u>	P

Number of Participating (P) countries: 8

Number of Observer (O) countries: 16

**TC
93**



TC 93 Structure

- Chair: Dr. JIM HEATON, UK (term ending 04 09), New Chair: Dr. OSAMU KARATSU, Japan
- Secretariat held by US NC (ANSI)
- TC Secretary Mr.. DIETER BERGMAN, US

- USNC advised by a Technical Advisor (TA) a Deputy TA and a Technical Advisory Group (TAG).

- Working groups are managed by one or two conveners
- and are formed from NC experts, Project Leaders

- WG1: Electronic data harmonization - ALEC STANCULESCU
- WG2: Component circuit and system description languages - SATOSHI KOJIMA, ALEX ZAMFIRESCU
- WG3: Reference model for electronic design interchange format- HILARY KHAN
- WG5: Test, validation, conformance and qualification technologies- JIM ST PIERRE
- WG6: Library of reusable parts for electrotechnical products - JOHN MESSINA
- WG7: Testing of electrotechnical products - NARAYANAN RAMACHANDRAN
- JWG11: Product description standard for printed board, printed board assembly and testing in XML schema - DIETER BERGMAN

**TC
93**



TC 93 Publications

- Publications are
 - International Standards (IS)
 - Publicly Available Specifications (PAS)
 - Technical Reports (TR)
- 16 ISs and TRs done under TC93
- 4 new DUAL LOGO (IEC/IEEE) ISs
- A large Programme of Work

**TC
93**



As Flexible as Possible

- Since 1906 IEC worked on international standards
- Recent “market dynamics” and “technology fast evolution” were reflected in changes on how standards are produced in IEC
 - **Synchronized IEEE and IEC ballots**
 - **IEC “fast track” and other mechanisms (like PAS)**
 - **IEC-IEEE DUAL LOGO Agreement**

**TC
93**



DUAL LOGO Advantages

- Avoidance of effort duplication
- Recognition of contribution
- Intellectual Property rights
- Easier maintenance procedures

**TC
93**



Highlights of IEC/IEEE Dual Logo Agreement

- Approved IEEE Standards are eligible
- Documents Submitted to the IEC (SMB) for consideration
- Current plan is to have the appropriate IEC TC review document. No revisions can be made.
- Process is estimated to take about six months
- IEC national members will have the same rights regarding adoptions as with other IEC standards

**TC
93**



Identifying Dual Logo Candidates

- Candidates may be suggested by an IEEE Sponsor Chair, IEEE Working Group Chair, or by the IEC Technical Committee or the IEC Central Office.
- IEEE Staff reviews the Technical and Financial Aspects of the submission
- Appropriate Parties are contacted
 - IEEE Working Group Chair
 - IEEE Sponsor Chair
 - US TAG (if one exists)
 - Chair/Secretary of relevant IEC TC

**TC
93**



Dual Logo Process

- Candidate is formally submitted to the IEC Central Office
 - IEC reviews candidate
- IEC Central Office sends a Question of Principle (QP) ballot to the SMB
 - Should this document move forward as an IEC/IEEE dual logo document?
- If the ballot passes, the document is sent to the appropriate IEC TC for “fast-tracking”

**TC
93**



Fast-Track Process

- IEC TC reviews and votes on the document as a Final Draft International Standard (FDIS)
- If the vote on the FDIS is positive, then the document is published as a dual logo IEC/IEEE international standard

**TC
93**



How it will Look

NORME
INTERNATIONALE
INTERNATIONAL
STANDARD

CEI
IEC
6XXXX
Première édition
First edition
200X-XX

IEEE XXXX

Titre –

Partie x:

Title –

Part x:

Sample Front Cover



Numéro de référence
Reference number
CEI/IEC 6XXXX:200X
IEEE Std. XXXX:200X

4 / 5

138AC

NORME
INTERNATIONALE
INTERNATIONAL
STANDARD

CEI
IEC
6XXXX
Première édition
First edition
200X-XX

IEEE XXXX

Titre –

Partie x:

Title –

Part x:

Sample First Inside Page

© IEEE 2002. Droits de reproduction réservés. — Copyright - all rights reserved.
IEEE is a registered trademark in the U.S. Patent & Trademark Office, owned by the Institute of Electrical and Electronics Engineers, Inc.
Aucune partie de cette publication ne peut être reproduite ni utilisée sous quelque forme que ce soit et par aucun procédé, électronique ou mécanique, y compris la photocopie et les microfilms, sans l'accord écrit de l'IEEE ou de l'IEC.
No part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and recording, without permission in writing from the IEEE or the IEC.
International Electrotechnical Commission, 3, rue de Vaupes, PO Box 131, CH-1211 Geneva 20, Switzerland
Telephone: +41 22 919 02 11 Telex: +41 22 919 02 00 E-mail: inmail@iec.ch Web: www.iec.ch
The Institute of Electrical and Electronics Engineers, Inc., 445 Hoes Lane, Piscataway, NJ, 08854-1331 USA
Telephone: +1 732 962 3800 Telex: +1 732 562 1571 E-mail: stds-ieee@ieee.org Web: www.standards.ieee.org



Commission Electrotechnique Internationale
International Electrotechnical Commission
Internationaler Elektrotechnischer Ausschuss

5 / 5

138AC

TC 93



Current Dual Logo TC 93 Submissions

- IEEE Std 1497-2001 – IEEE Standard for Standard Delay Format (SDF) for the Electronic Design Process
- IEEE Std 1076-2002 – IEEE Standard VHDL Language Reference Manual
- IEEE Std 1364-2001 – IEEE Standard Verilog® Hardware Description Language
- IEEE Std 1076.4-2000 – IEEE Standard for VITAL ASIC (Application Specific Integrated Circuit) Modeling Specification

**TC
93**